

3030 Full Spectrum Datasheet





Features:

Slim Size SMD Package: Design Flexibility
High Lumen Output and High Efficacy
Stable Performance & Great CCT Unity
Full Spectrum 380-850nm
Forward Voltage 3V, 6V Available
Environmental Friendly; ROHS Compliance

Customized Service Available

Applications:

LED Module, Illuminated Advertising

Tube Light, Panel Light, Ceiling Lamp and other LED Indoor Lights

Flood Light, High Bay Light, Tunel Light and other LED Outdoor Lights

LED Aquarium Light, LED Plant Growing Light..



TABLE OF CONTENTS

PRODUCT NAMING RULES	3
CHARACTERISTICS	4
LUMINOUS FLUX CHARACTERISTIC	5
CHARACTERISTIC CURVES	6
CHARACTERISTIC CURVES	7
FULL SPECTRUM CURVES	8-17
RELIABILITY TESTS	18
SOLDERING CONDITIONS	19
DIMENSION	20
PACKAGING	21
PRECAUTIONS	22
PRECAUTIONS	23



PRODUCT NAMING RULES

XXXX	FSXX	Х	X	XXX		XX
Туре	Color	Chip QTY	Beam Angle	Brightness V	oltage	
3030	FS01: Full Spectrum 1	1: 1EA	0: 120°/140°	70: 70-80LM	3V	
	FS03: Full Spectrum 3	2: 2EA		120: 120-130LM	6V	
	FS11: Full Spectrum 11	3: 3EA				
	Type 8030	Type Color	Type Color Chip QTY 3030 FS01: Full Spectrum 1 1: 1EA FS03: Full Spectrum 3 2: 2EA	Type Color Chip QTY Beam Angle 3030 FS01: Full Spectrum 1 1: 1EA 0: 120°/140° FS03: Full Spectrum 3 2: 2EA	Type Color Chip QTY Beam Angle Brightness V 3030 FS01: Full Spectrum 1 1: 1EA 0: 120°/140° 70: 70-80LM FS03: Full Spectrum 3 2: 2EA 120: 120-130LM	Type Color Chip QTY Beam Angle Brightness Voltage 3030 FS01: Full Spectrum 1 1: 1EA 0: 120°/140° 70: 70-80LM 3V FS03: Full Spectrum 3 2: 2EA 120: 120-130LM 6V

....



CHARACTERISTICS

Parameter	Unit	Min	Typical	Max
Power Dissipation 1	mW		1050	
Forward Current 1	mA		350	
Forward Current 2	mA		150	
Forward Voltage 1	V	2,8		3,4
Forward Voltage 2	V	6.0		6,4
Color Rendering Index	Ra		90	
Beam Angle 201/2	deg.		120	
Reverse Current	uA			10
Reverse Voltage	V			5
Operating Temperature Top	°C	-40		+60
Storage Temperature Tst	$^{\circ}\mathrm{C}$	-40		+85
Testing Point Tc	°C			55
Junction Temperature Tj	$^{\circ}\mathrm{C}$			120
Reverse Current (Vr=5V) Ir	uA			5
Related thermal resistance Rj-c	°C/W		8	
ESD (HBM)	V			2000
Reflow Soldering(Lead-Free) ST	$^{\circ}\!\mathbb{C}$			260



LUMINOUS FLUX CHARACTERISTIC

Specifications (IF=350mA, Tc=25 $^{\circ}$ C)

Light Color	Color Temperature (K)	CRI	1W, 3V @350mA LM	Model No.
Full Spectrum 01	1200-1300K	/	120-130	LKL-3030FS0110120-3V
Full Spectrum 03	2900-3000K	90	70-80	LKL-3030FS031070-3V
Full Spectrum 04	6800-7000K	90	70-80	LKL-3030FS041070-3V
Full Spectrum 05	2900-3000K	90	70-80	LKL-3030FS051070-3V
Full Spectrum 07	1700-1800K	/	120-130	LKL-3030FS0710120-3V
Full Spectrum 09	1200-1300K	/	120-130	LKL-3030FS0910120-3V
Full Spectrum 11	4700-4900K	/	120-130	LKL-3030FS1110120-3V
Full Spectrum 13	4200-4400K	90	70-80	LKL-3030FS131070-3V
Full Spectrum 15	2000-2200K	/	120-130	LKL-3030FS1510120-3V
Full Spectrum 16	100000K	/	120-130	LKL-3030FS1610120-3V

Specifications (IF=150mA, Tc=25 $^{\circ}\mathrm{C}$)

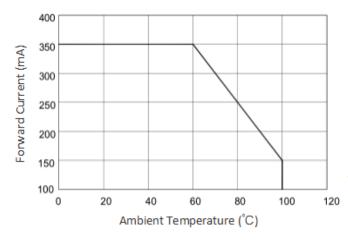
Light Color	Color Temperature (K)	CRI	1W, 6V @150mA LM	Model No.
Full Spectrum 01	1200-1300K	/	120-130	LKL-3030FS0110120-6V
Full Spectrum 03	2900-3000K	90	70-80	LKL-3030FS031070-6V
Full Spectrum 04	6800-7000K	90	70-80	LKL-3030FS041070-6V
Full Spectrum 05	2900-3000К	90	70-80	LKL-3030FS051070-6V
Full Spectrum 07	1700-1800K	/	120-130	LKL-3030FS0710120-6V
Full Spectrum 09	1200-1300K	/	120-130	LKL-3030FS0910120-6V
Full Spectrum 11	4700-4900K	/	120-130	LKL-3030FS1110120-6V
Full Spectrum 13	4200-4400K	90	70-80	LKL-3030FS131070-6V
Full Spectrum 15	2000-2200K	/	120-130	LKL-3030FS1510120-6V
Full Spectrum 16	100000K	/	120-130	LKL-3030FS1610120-6V

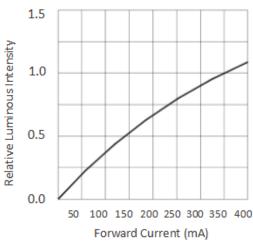
Copyright ©2018 LEKOLED Technology Corporation. All rights reserved. The information in this document is subject to change without notice. www.lekoled.com

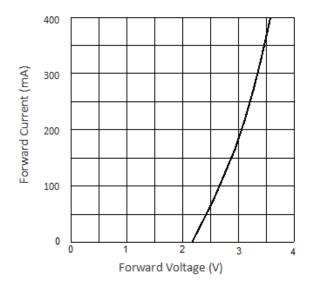


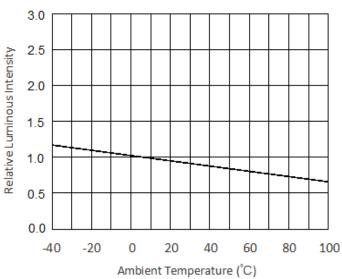
TYPICAL CHARACTERISTIC CURVES

IF=350mA





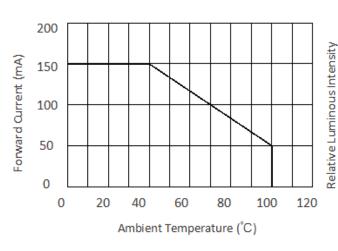


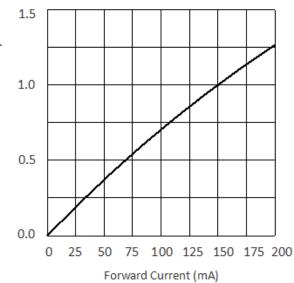


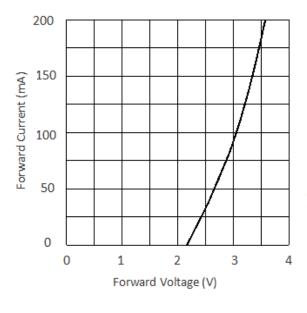


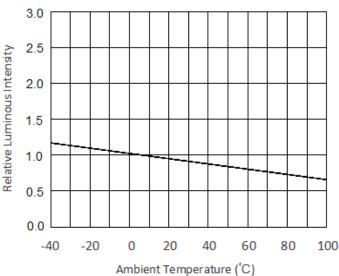
TYPICAL CHARACTERISTIC CURVES

IF=150mA



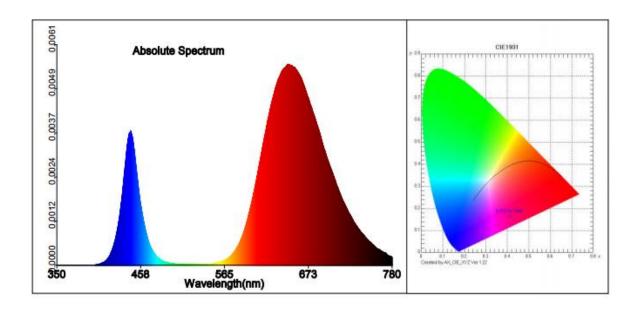








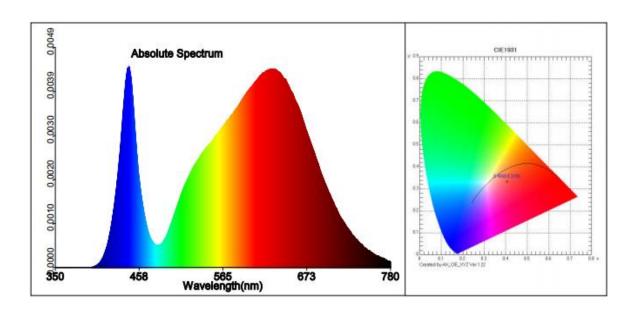
NO. 1



E= 49.0 lx	E(fc)=4.5	54948 fc			
CIE x= 0.4103 Tc=1211 K Pur=55.8 % Duv=0.12108	CIE y= 0 Lp=661.0 Ratio_R:	0 nm	CIE u'=0.3957 HW=94.3 nm Ratio_G=13.8 %		CIE v'=0.3559 Ld=610.2 nm Ratio_B=7.6 %
Ra=-17.4 R4= 16 R8= 44 R12=-515	R1= 57 R5= 12 R9= 54 R13= 13		R2=-18 R6=-121 R10=-155 R14= -4		R3=-98 R7=-31 R11= 40 R15= 51
SDCM= 0.2() White Class:OUT					
Ech-A=0.15406 W/m2 Eb=0.11689 W/m2		E2=0.73919 W/m2 Ech-B=0.1342 W/m2 Ey=0.013469 W/m2 Erb_Ratio=3.8317		Ef=0.1	9=2.9661 µmol/(m·s) 16144 W/m2 44791 W/m2



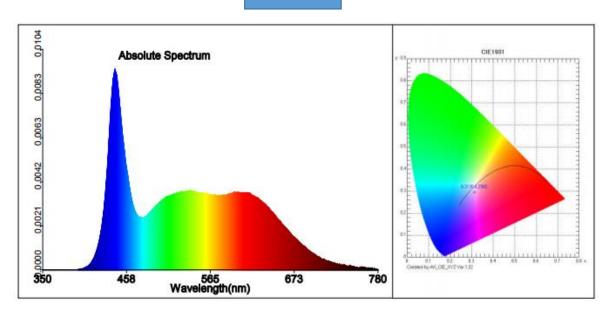
NO. 3



E= 220.7 lx	E(fc)=20.	.5151 fc			
CIE x= 0.4068 Tc=2910 K Pur=22.1 % Duv=-0.02696	CIE y= 0. Lp=449.0 Ratio_R=	nm (CIE u'=0.2629 HW=26.2 nm Ratio_G=71.0 %	Ĺ	CIE v'=0.4851 .d=609.8 nm Ratio_B=2.7 %
Ra=92.1 R4= 87 R8= 91 R12= 89	R1= 97 R5= 95 R9= 92 R13= 96		R2= 95 R6= 92 R10= 90 R14= 94	F	R3= 92 R7= 88 R11= 85 R15= 94
SDCM= 0.3() White Class:OUT					
E1=0.86312 W/m2 Ech-A=0.12159 W/m2 Eb=0.16281 W/m2 Ep=0.77237 Wphyto/m2 PPFDf=5.8502E-001 µmol	l/(m2·s)	E2=0.96281 W/r Ech-B=0.13853 Ey=0.27285 W/r Erb_Ratio=2.628	W/m2 m2	Ef=0.099	3.2011 µmol/(m·s) 9952 W/m2 796 W/m2



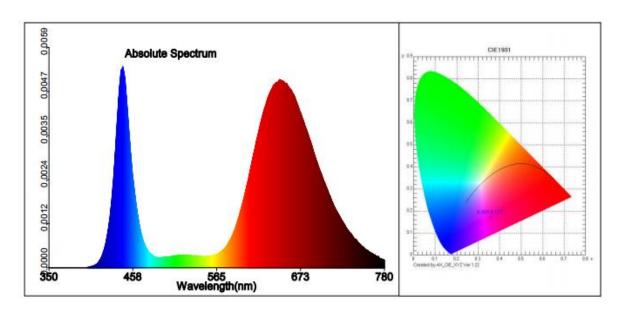
NO. 4



E= 284.1 lx	E(fc)=26.	4054 fc				
CIE x= 0.3130 Tc=6816 K Pur=11.6 % Duv=-0.01470	CIE y= 0. Lp=447.0 Ratio_R=	nm (CIE u'=0.2110 HW=26.5 nm Ratio_G=76.2 %		CIE v'=0.4499 Ld=448.4 nm Ratio_B=6.4 %	
Ra=90.3 R4= 88 R8= 90 R12= 79	R1= 90 R5= 92 R9= 73 R13= 91		R2= 94 R6= 89 R10= 89 R14= 91		R3= 86 R7= 93 R11= 86 R15= 86	
SDCM= 0.3() White Class:OUT						
E1=1.0696 W/m2 Ech-A=0.078194 W/m2 Eb=0.37545 W/m2 Ep=0.90075 Wphyto/m2 PPFDf=2.2503E-001 µmol/(m2·s)		E2=1.1077 W/m2 Ech-B=0.11615 W/m2 Ey=0.38903 W/m2 Erb_Ratio=0.8146		PPFD=4.858 µmol/(m·s) Ef=0.038201 W/m2 Er=0.30584 W/m2		



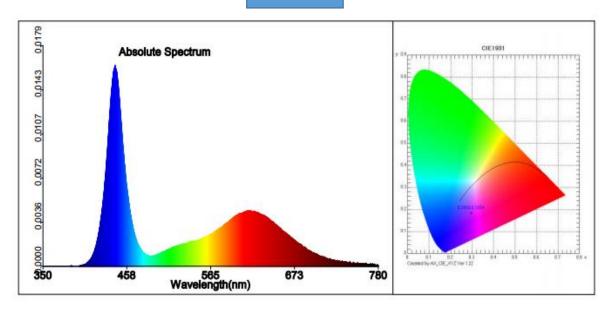
NO. 5



E= 66.7 lx	E(fc)=6.1	19713 fc			
CIE x= 0.3581 Tc=1768 K Pur=49.2 % Duv=-0.12360	CIE y= 0 Lp=449.0 Ratio_R=	0 nm	CIE u'=0.3302 HW=23.7 nm Ratio_G=34.2 %	l	CIE v'=0.3551 Ld=610.2 nm Ratio_B=8.6 %
Ra=2.0 R4= 75 R8= 53 R12=-334	R1= 9 R5=-25 R9=-65 R13=-21		R2=-18 R6=-91 R10=-145 R14= 41	F	R3=-19 R7= 31 R11= 46 R15= -9
SDCM= 0.2() White Class:OUT E1=0.62799 W/m2 Ech-A=0.13376 W/m2 Eb=0.16913 W/m2 Ep=0.55871 Wphyto/m2 PPFDf=8.4310E-001 µmo	l/(m2·s)	E2=0.77204 W/r Ech-B=0.11571 Ey=0.042269 W Erb_Ratio=2.464	W/m2 /m2	Ef=0.14	3.1203 µmol/(m·s) 442 W/m2 674 W/m2



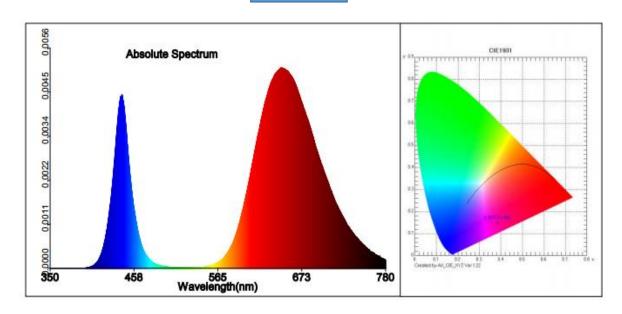
NO. 7



E= 202.8 lx	E(fc)=18.	.8464 fc			
CIE x= 0.2958 Tc=100000 K Pur=42.4 % Duv=-0.08083	CIE y= 0. Lp=447.0 Ratio_R=	nm (CIE u'=0.2567 HW=24.9 nm Ratio_G=63.2 %		CIE v'=0.3581 Ld=380.0 nm Ratio_B=8.2 %
Ra=41.2 R4= 34 R8= 11 R12= 52	R1= 15 R5= 33 R9=-191 R13= 21		R2= 52 R6= 48 R10= 30 R14= 67		R3= 56 R7= 80 R11= 23 R15=-17
SDCM= 0.2() White Class:OUT					
E1=1.144 W/m2 Ech-A=0.094375 W/m2 Eb=0.53494 W/m2 Ep=0.9637 Wphyto/m2 PPFDf=3.2785E-001 µmo	l/(m2·s)	E2=1.2004 W/m Ech-B=0.12661 Ey=0.22667 W/r Erb_Ratio=0.715	W/m2 n2	Ef=0.0	=5.1242 µmol/(m·s) 056532 W/m2 058287 W/m2



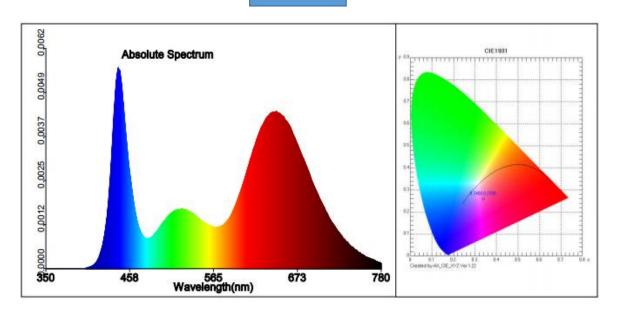
NO. 9



E= 47.9 lx	E(fc)=4.4	45347 fc			
CIE x= 0.3837 Tc=1289 K Pur=57.5 % Duv=0.13714	CIE y= 0 Lp=660.0 Ratio_R:	0 nm	CIE u'=0.3821 HW=95.7 nm Ratio_G=15.1 %		CIE v'=0.3331 Ld=610.2 nm Ratio_B=8.0 %
Ra=-24.6 R4= 4 R8= 44 R12=-516	R1= 54 R5= 10 R9= 45 R13= 6		R2=-27 R6=-132 R10=-172 R14=-11		R3=-110 R7=-40 R11= 27 R15= 40
SDCM= 0.1() White Class:OUT					
Ech-A=0.13219 W/m2 Ec Eb=0.1394 W/m2 Ey		E2=0.71745 W/m2 Ech-B=0.11071 W/m2 Ey=0.014353 W/m2 Erb_Ratio=2.986		Ef=0.1	=2.8754 µmol/(m·s) 4791 W/m2 41626 W/m2



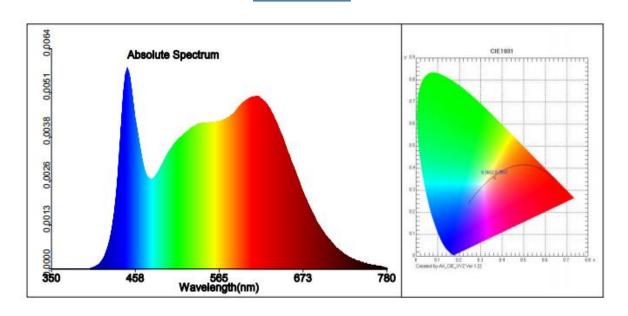
NO. 11



E= 132.1 lx	E(fc)=12	.2804 fc			
CIE x= 0.3400 Tc=4710 K Pur=22.3 % Duv=-0.05329	CIE y= 0 Lp=447.0 Ratio_R:	nm (CIE u'=0.2503 HW=24.7 nm Ratio_G=64.2 %		CIE v'=0.4298 Ld=610.2 nm Ratio_B=6.2 %
Ra=45.8 R4= 35 R8= -4 R12= 43	R1= 30 R5= 35 R9=-145 R13= 35		R2= 62 R6= 60 R10= 31 R14= 83		R3= 79 R7= 69 R11= 25 R15= 2
SDCM= 0.3() White Class:OUT E1=0.72767 W/m2 Ech-A=0.11241 W/m2 Eb=0.19437 W/m2 Ep=0.63509 Wphyto/m2 PPFDf=6.8427E-001 µmo	l/(m2·s)	E2=0.84431 W/r Ech-B=0.10372 Ey=0.15306 W/r Erb_Ratio=1.957	W/m2 m2	Ef=0.11	3.5175 µmol/(m·s) 1696 W/m2 8052 W/m2



NO. 13



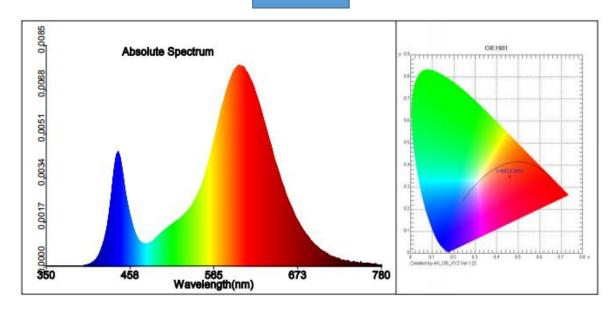
Test parameter:

PPFDf=3.2254E-001 µmol/(m2·s)

E= 333.1 lx	E(fc)=30.9572	2 fc			
CIE x= 0.3662 Tc=4277 K Pur=16.9 % Duv=-0.00526	CIE y= 0.3567 Lp=452.0 nm Ratio_R=20.1	ı	CIE u'=0.2237 HW=34.5 nm Ratio_G=74.9 %		CIE v'=0.4903 Ld=582.3 nm Ratio_B=5.0 %
Ra=97.3 R4= 99 R8= 97 R12= 79	R1= 98 R5= 98 R9= 95 R13= 98		R2= 98 R6= 95 R10= 98 R14= 98		R3= 97 R7= 97 R11= 97 R15= 97
SDCM= 0.4() White Class:OUT					
E1=1.1474 W/m2 Ech-A=0.094271 W/m2 Eb=0.27442 W/m2 Ep=0.99299 Wphyto/m2	Ech Ey=	=1.2016 W/m2 h-B=0.12282 V =0.44644 W/m o_Ratio=1.557	N/m2 n2	Ef=0.0	5.4105 µmol/(m·s) 54369 W/m2 2738 W/m2



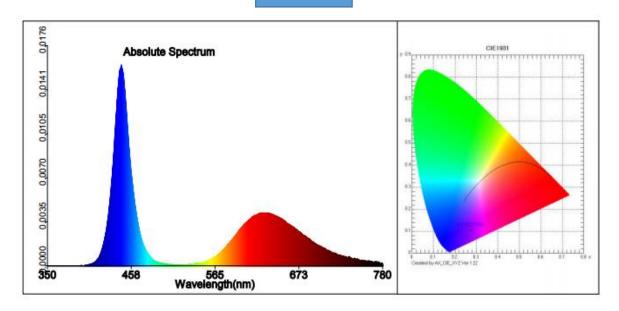
NO. 15



E= 307.9 lx	E(fc)=28	.6185 fc			
CIE x= 0.4603 Tc=2197 K Pur=42.9 % Duv=-0.02341	CIE y= 0 Lp=609.0 Ratio_R=) nm	CIE u'=0.2936 HW=92.7 nm Ratio_G=66.2 %	L	CIE v'=0.5013 .d=600.4 nm Ratio_B=2.3 %
Ra=75.2 R4= 68 R8= 43 R12= 82	R1= 80 R5= 82 R9= 0 R13= 85		R2= 96 R6= 90 R10= 95 R14= 89	F	R3= 79 R7= 65 R11= 67 R15= 74
SDCM= 0.3() White Class:OUT					
E1=1.048 W/m2 Ech-A=0.091626 W/m2 Eb=0.1642 W/m2 Ep=0.95354 Wphyto/m2 PPFDf=2.1342E-001 µmo	l/(m2·s)	E2=1.0841 W/m Ech-B=0.14551 Ey=0.36369 W/r Erb_Ratio=3.173	W/m2 m2	Ef=0.036	5.1078 µmol/(m·s) 53 W/m2 102 W/m2



NO. 16



E= 92.5 lx	E(fc)=8.59386	6 fc				
CIE x= 0.2735 Tc=100000 K Pur=64.4 % Duv=-0.14787	CIE y= 0.1059 Lp=449.0 nm Ratio_R=51.8	1	CIE u'=0.2937 HW=23.9 nm Ratio_G=30.8 %		CIE v'=0.2560 Ld=380.0 nm Ratio_B=17.4 %	
Ra=-67.8 R4=-11 R8=-50 R12=-188	R1=-85 R5=-66 R9=-455 R13=-113		R2=-111 R6=-110 R10=-357 R14= 3		R3=-114 R7= 5 R11=-38 R15=-166	
SDCM= 0.1() White Class:OUT						
E1=0.92845 W/m2 Ech-A=0.09374 W/m2 Eb=0.4968 W/m2 Ep=0.77968 Wphyto/m2 PPFDf=5.5020E-001 µmol	Ech Ey= Erb	=1.0241 W/m2 h-B=0.10334 \ =0.054004 W/ o_Ratio=0.760	W/m2 m2	Ef=0.0	=4.1796 µmol/(m·s 95869 W/m2 37792 W/m2)



RELIABILITY TESTS

Sample QTY **Test Items Test Conditions** Ac/Re 0/1 IF=150-350mA, Ta=25 [°]C x6000hrs 22 **Aging Test** IF=150-350mA, Ta=85 °C x6000hrs 22 0/1 High Temperature Storage 100°C x1000hrs 22 0/1 Low Temperature Storage -40°C x1000hrs 0/1 22 High Temp & Humidity IF=150-350mA, 85 °C, 85% RH for 6000hrs 22 0/1 **Temperature Shock** 0/1 -40°Cx30 min & +100°Cx30 min, 100cycle 22 ESD(HBM) 2000V HBM/ 1 Time 10 0/1

Criteria for Judging LED Failure (Tc= 25 °C)

Items	Symbol	Test Conditions	Criteria for Judging LED Failure
Forward Voltage	VF	IF=150-350mA	>U x 1.1
Reverse Current	IR	VR=5V	IR>/= 10μA
Lumen	ФV	IF=150-350mA	<s 0.7<="" td="" x=""></s>

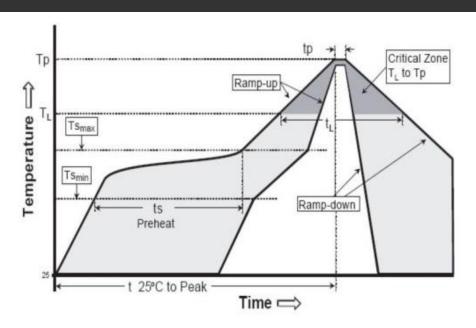
U refers to max value; S refers to initial value.

Notes: Judging criteria based on Tc=25 $^{\circ}$ C.



TYPICAL CHARACTERISTIC CURVES

REFLOW SOLDERING PROFILE

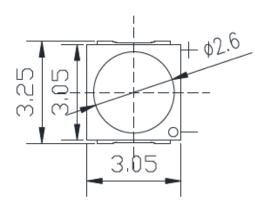


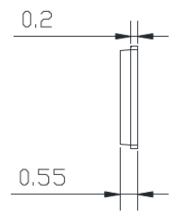
Profile Features	Lead-free solder	Lead solder	Soldering by Manual
Ramp-up Speed(Ts max to Tp)	3 °C/ second max.	3 °C/ second max.	
Preheat: Min. Temperature(Tsmin)	150 °C	100 °C	
Preheat: Max.Temperature(Tsmax)	200 °C	150 °C	
Preheat: Time (tsmin to tsmax)	60~180 seconds	60~120 seconds	
Temperature to Keep: (TL)	217 °C	183 °C	Max. temperature: 350°C
Time to Keep: (tL)	60~150 seconds	60~150 seconds	3 seconds/1 time
Peak Temperature (Tp)	eak Temperature (Tp) 260 °C		
Time within the peak temperature (tp)	20~40 seconds	10~30 seconds	
Ramp-down Speed	6°C/ second max.	6°C/ second max.	
Time to the peak Temperature	8 minutes max.	6 minutes max.	

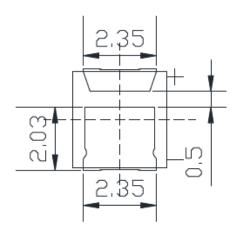


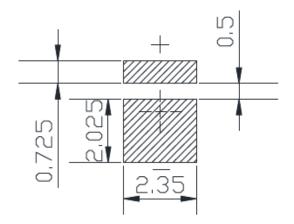
DIMENSIONS

Unit: mm









Notes:

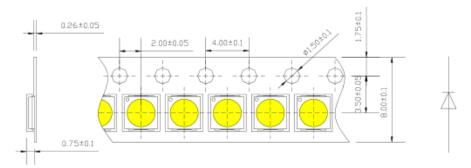
*All dimensions are in millimeters.(tolerance:±0.2mm)

*The appearance and specifications of the product may be changed for improvement without notice.

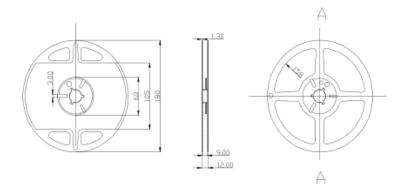


PACKAGING

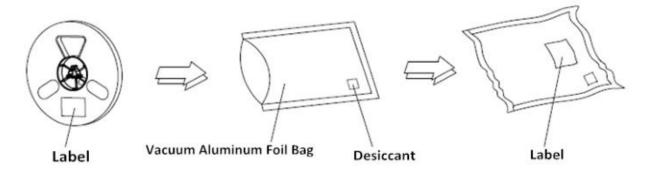
Tape Specifications (Units: mm)



Reel Dimensions



Moisture Resistant Packaging





PRECAUTIONS

Storage

- 1. Moisture proof and anti-electrostatic package with moisture absorbent material is used, to keep moisture to aminimum.
- 2. Before opening the package, the product should be kept at 30°C or less and humidity less than 60% RH, and beused within a year.
- 3. After opening the package, the product should be stored at 30° C or less and humidity less than 10%RH, and besoldered within 24 hrs (1day). It is recommended that the product be operated at the workshop condition of 30° C or less and humidity less than 60%RH.
- 4. If the moisture absorbent material has fade away or the LEDs have exceeded the storage time, baking treatment should be performed based on the following condition: (80±5) °C for 24 hours.

Static Electricity

- 1. Static electricity or surge voltage damages the LEDs. Damaged LEDs will show some unusual characteristic such as the forward voltage becomes lower, or the LEDs do not light at the low current. even not light.
- 2. All devices, equipment and machinery must be properly grounded. At the same time, it is recommended that wrist bands or anti-electrostatic gloves, anti-electrostatic containers be used when dealing with the LEDs.

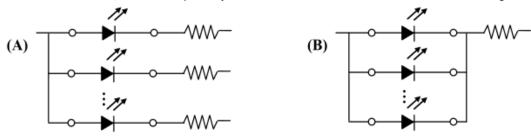
Vulcanization

LED curing is due to sulfur being in bracket and the +1 price of silver in the chemical reaction generated Ag2S in the process. It will lead to the capacity of reflecting of silver layer reducing, light color temperature drift and serious decline, seriously affecting the performance of the product. So we should take corresponding measures to avioding vulcanization, such as to avoid using sulphur volatile substances and keeping away from high sulphur content of the material.

Design Consideration

- 1. In designing a circuit, the current through each LED must not exceed the absolute maximum rating specified for each LED. In the meanwhile, resistors for protection should be applied, otherwise slight voltage shift will cause big current change, burn out may happen.
- 2. It is recommended to use Circuit A which regulates the current flowing through each LED rather than Circuit B.

 When driving LEDs with a constant voltage in Circuit B, the current through the LEDs may vary due to the variation in Forward Voltage (VF) of the LEDs. In the worst case, some LED may be subjected to stresses in excess of the Absolute Maximum Rating.



3. Thermal Design is paramount importance because heat generation may result in the Characteristics decline, such as brightness decreased, Color changed and so on. Please consider the heat generation of the LEDs when making the system design.



PRECAUTIONS

Safety Advice For Human Eyes

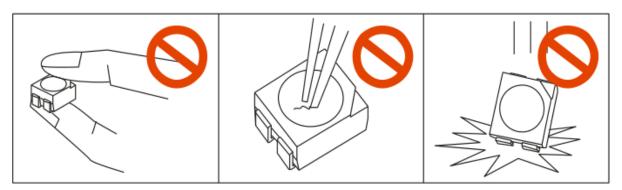
Viewing direct to the light emitting center of the LEDs, especially those of great Luminous Intensity will cause great hazard to human eyes. Please be careful.

The safe temperature for LEDs working

The high temperature will make the LEDs' Luminous Intensity decreased radically, if LEDs worked in hoteyes. Please be careful. environment for a long time, they will be disabled easily. When LEDs are working in a closed array, we suggest that the LEDs' surface temperature should be lower than 55° C and the legs' temperature should be lower than 75° C.

Others

1. When handling the product, touching the encapsulant with bare hands will not only contaminate its surface, but also affect on its optical characteristics. Excessive force to the encapsulant might result in catastrophic failure of the LEDs due to Die breakage or wire deformation. For this reason, please do not put excessive stress on LEDs, especially when the LEDs are heated such as during Reflow Soldering.



2. The epoxy resin of encapsulant is fragile, so please avoid scratch or friction over the epoxy resin surface. While handling the product with tweezers, do not hold by the epoxy resin, be careful.

Copyright ©2018 LEKOLED Technology Corporation. All rights reserved. The information in this document is subject to change without notice. www.lekoled.com